

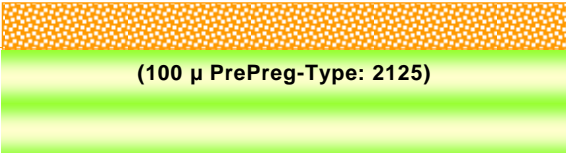
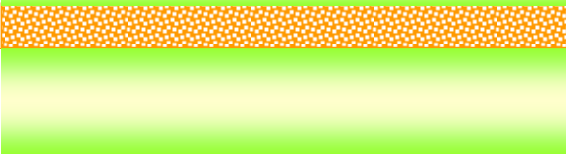
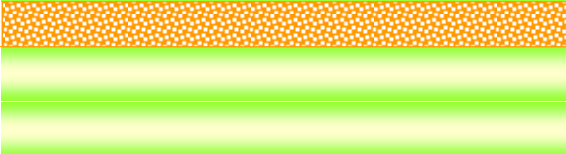
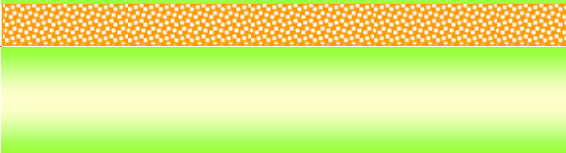
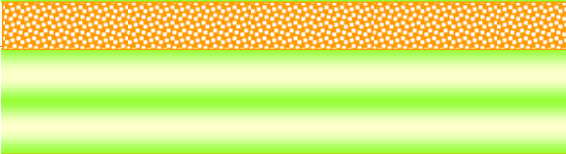

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 174 FR4 70 L36.70 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_174_FR4_70_L36.70_p10

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	70 μ	Copper		A1			
	100 μ	Prepreg					
	100 μ	Prepreg					
Layer-2	70 μ	Copper			A2		
	360 μ	L-FR4					
Layer-3	70 μ	Copper				B	
	100 μ	Prepreg					
	100 μ	Prepreg					
Layer-4	70 μ	Copper					A1
	360 μ	L-FR4					
Layer-5	70 μ	Copper		A2			
	100 μ	Prepreg					
	100 μ	Prepreg					
Layer-99	70 μ	Copper					

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